MSKSEMI 美森科













ESD

VS

TSS

MOV

GDT

PIFD

TL431
Product specification





Features

- Programmable output Voltage to 36 V
- Low dynamic output impedance
- Sink current capability of 1 to 100 mA
- Low output noise voltage
- Fast turn on response

Reference News

SOT-23	MARKING
1 2 3	431

1	Reference	
2	Cathode	
3	Anode	

Absolute Maximum Ratings (Ta = 25 °C, unless otherwise noted.)

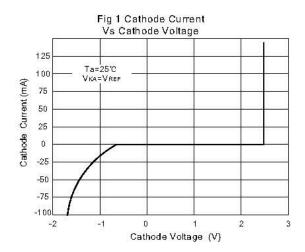
Parameter	Symbol	Value	Unit
Cathode Voltage	V_{KA}	36	V
Cathode Current Range (Continuous)	I _{KA}	- 100 to + 150	mA
Reference Input Current Range	I _{REF}	- 0.05 to + 10	mA
Power Dissipation	P_D	350	mW
Operating Temperature Range	T _{opr}	- 25 to + 85	°C
Junction Temperature	T _j	150	°C
Storage Temperature Range	T _{stg}	- 65 to + 150	°C

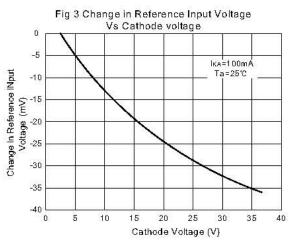
Recmmended Operating Conditions

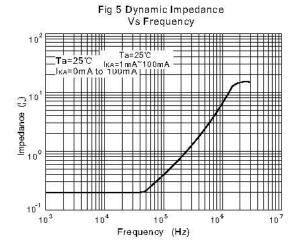
Parameter	Symbol	Min.	Max.	Unit
Cathode Voltage	V_{KA}	V_{REF}	36	V
Cathode Current	I _{KA}	1	100	mA

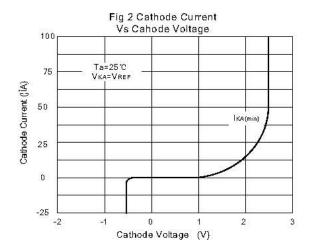
Characteristics at T_a = 25 °C

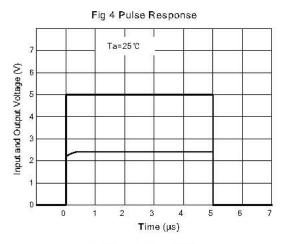
Parameter	Symbol	Min.	Тур.	Max.	Unit
Reference Input Voltage at $V_{KA} = V_{REF}$, $I_{KA} = 10$ mA	V_{REF}	2.488	2.495	2.502	V
Deviation of Reference Input Voltage Over Temperatue at V_{KA} = V_{REF} , I_{KA} = 10 mA, - 25 °C ≤ T_a ≤ + 85 °C	ΔV _{REF} /ΔT	-	4.5	17	mV
Ratio of Change in Reference Input Voltage to the Change in Cathode Voltage at I_{KA} = 10 mA ΔV_{KA} = 10 V to V_{REF} ΔV_{KA} = 36 V to 10 V	$\Delta V_{REF}/\Delta V_{KA}$		-1.0 -0.5	-2.7 -2	mV/V
Reference Input Current at I_{KA} = 10 mA, R1 = 10 K Ω , R2 = ∞	I _{REF}	-	1.5	4	μA
Deviation of Reference Input Current Over Full Temperatue at I_{KA} = 10 mA, R1 = 10 K Ω , R2 = ∞ , - 25 °C \leq T _a \leq + 85 °C	$\Delta I_{REF}/\Delta T$	ı	0.4	1.2	μΑ
Minimum Cathode Current for Regulation at $V_{KA} = V_{REF}$	I _{KA(min)}	ı	0.45	1	mA
Off-Stage Cathode Current at $V_{KA} = 36 \text{ V}$, $V_{REF} = 0$	I _{KA(OFF)}	-	0.05	1	μΑ
Dynamic Impedance at $V_{KA} = V_{REF}$, $I_{KA} = 1$ to 100 mA, $f \le 1$ KHz	Z _{KA}	-	0.15	0.5	Ω

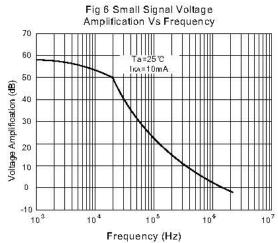






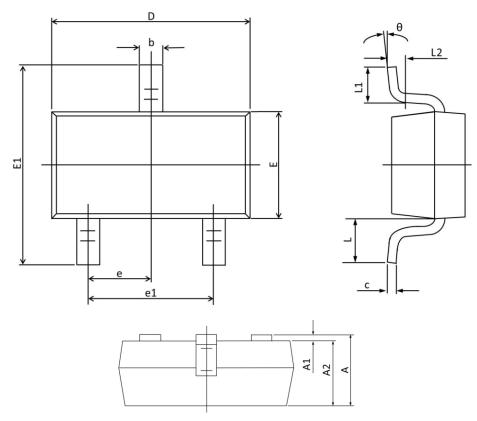








SOT-23 PACKAGE INFORMATION



Symbol	<u>DimensionsIn</u> <u>Millimeters</u>		Dimensions	Dimensions In Inches	
Symbol	Max	Min	Max	Min	
A	1.150	0.900	0.045	0.035	
A1	0.100	0.000	0.004	0.000	
A2	1.050	0.900	0.041	0.035	
b	0.500	0.300	0.020	0.012	
c	0.150	0.080	0.006	0.003	
D	3.000	2.800	0.118	0.110	
E	1.400	1.200	0.055	0.047	
E1	2.550	2.250	0.100	0.089	
e	0.95 TYP.		0.037	TYP.	
e1	2.000	1.800	0.079	0.071	
L	0.55 REF.		0.022	REF.	
L1	0.500	0.300	0.020	0.012	
L2	0.25 TYP.		0.01	TYP.	
θ	8 °	0°	8°	0 °	

REELSPECIFICATION

P/N	PKG	QTY
TL431	SOT-23	3000



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